

# 曜凌光電股份有限公司

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### RC0802A-GHY-CSV

### **SPECIFICATION**

### **CUSTOMER:**

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

Release DATE:



## **Revision History**

VERSION	DATE	REVISED PAGE NO.	Note
0	2012/05/18		First issue
Α	2014/12/12		Remove IC
			information



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### 1.General Specification

The Features is described as follow:

■ Module dimension: 58.0 x 32.0 x 13.2 (max.) mm

■ View area: 38.0 x 16.0 mm

Active area: 27.81 x 11.5 mm

Number of Characters: 8 characters x 2 Lines

■ Dot size: 0.56 x 0.66 mm

■ Dot pitch: 0.60 x 0.70 mm

■ Character size: 2.96 x 5.56 mm

■ Character pitch: 3.55 x 5.94 mm

■ LCD type: STN Positive, Gray Transflective

■ Duty: 1/16

View direction: 6 o'clock

■ Backlight Type: LED, Yellow Green

■ IC:ST7066U



### 2. Module Classification Information

<u>R</u>	<u>C</u>	<u>0802</u>	<u>A</u>	_	<u>G</u>	<u>H</u>	<u>Y</u>	_	<u>CSV</u>
①	2	3	4	_	(5)	6	7	_	8

Item	Description							
1	R : Raystar O	ptronics Inc.	-					
2	Dioploy	C: Character Type,		T:TAB Type				
	Display	G: Graphic Type		X:COG Type				
3	Number of dot	s: Character 08 words, 0	2 Lines.	-				
4	Serials code :							
		P→TN Positive, Gray		V→FSTN Ne	egative, Blue			
		N→TN Negative,		T→FSTN Ne	egative, Black			
		L→VA Negative		D→FSTN Ne	egative (Double film)			
		H→ HTN Positive, Gray		F→FSTN Po	ositive			
5	LCD	I→HTN Negative, Black		K→FSC Neg	gative			
		U→HTN Negative, Blue		S→FSC Pos	sitive			
		B→STN Negative, Blue		E→ISTN Ne	gative, Black			
		G→STN Positive, Gray		C→CSTN Negative, Black				
		Y→STN Positive, Yellow	Green	A→ASTN Negative, Black				
		A: Reflective, N.T, 6:00		K: Transflective, W.T,12:00				
	Polarizer	D: Reflective, N.T, 12:00		1: Transflective, U.T,6:00				
	Type,	G: Reflective, W. T, 6:00		4: Transflective, U.T.12:00				
	Temperature	J: Reflective, W. T, 12:0	0	C: Transmissive, N.T,6:00				
6	range,	0: Reflective, U. T, 6:00		F: Transmis	nissive, N.T,12:00			
		3: Reflective, U. T, 12:0	ctive, U. T, 12:00		I: Transmissive, W. T, 6:00			
	View	B: Transflective, N.T,6:0	00	L: Transmis	sive, W.T,12:00			
	direction	E: Transflective, N.T.12		2: Transmis	sive, U. T, 6:00			
		H: Transflective, W.T,6:			sive, U.T,12:00			
	4	N→ Without backlight	W→LE	), White	H→LED, High light White			
		P→EL, Blue	A→LED		S→LED, Full color			
	1	T→EL, Green	R→LED	, Red	J→DIP LED, Blue			
7	Backlight	D→EL, White		), Orange	K→DIP LED, White			
	Baorangin	M→EL, Yellow Green	B→LED		E→DIP LED, Yellow			
		F→CCFL, White		, Dual color	L→DIP LED, Amber			
		Y→LED, Yellow Green	C→LED	, Full color	I→DIP LED, Red			
		G→LED, Green						
8	Special code	CS:English and Cyrillic s		ont				
		V : Build in negative volta	age					

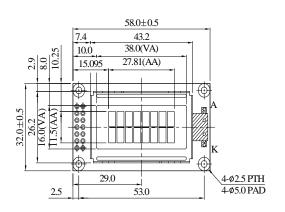


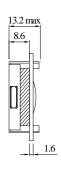
## 3.Interface Pin Function

Pin No.	Symbol	Level	Description
1	$V_{SS}$	0V	Ground
2	$V_{DD}$	3.3V	Supply Voltage for logic
3	NC	_	No connection
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read L: Write
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line



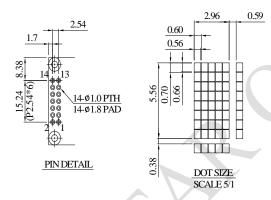
## 4. Contour Drawing & Block Diagram



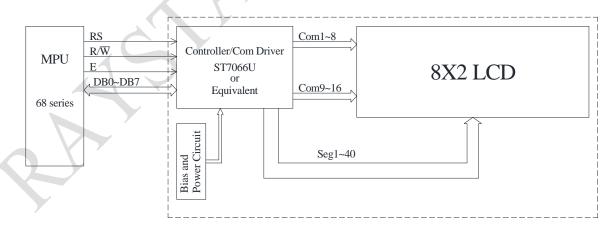


LED B/L

PIN NO.	SYMBOL
1	Vss
2	Vdd
3	NC
4	RS
5	R/W
6	Е
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7



The non-specified tolerance of dimension is  $\widehat{\mbox{1D}}.3\mbox{ mm}$  .



Character located DDRAM address DDRAM address

1 2 3 4 5 6 7 8 00 01 02 03 04 05 06 07 40 41 42 43 44 45 46 47



#### **5.Character Generator ROM Pattern**

Table.2



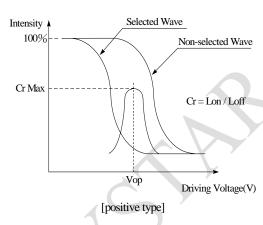


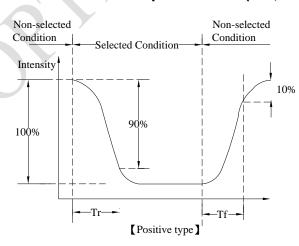
### **6.Optical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ	CR≧2	0	_	20	ψ= 180°
	θ	CR≧2	0	_	40	ψ= 0°
	θ	CR≧2	0	_	30	ψ= 90°
	θ	CR≧2	0		30	ψ= 270°
Contrast Ratio	CR	_	_	3	7	_
Danasa Tima	T rise	_	_	150	200	ms
Response Time	T fall	_	Q.	150	- 30 $ψ = 90$ $-$ 30 $ψ = 27$ $-$ 150 200 ms	ms

#### **Definition of Operation Voltage (Vop)**

#### **Definition of Response Time (Tr, Tf)**



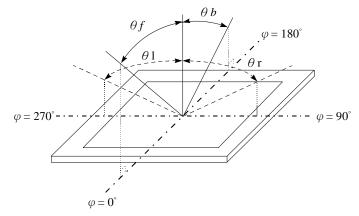


#### **Conditions:**

Operating Voltage : Vop Viewing Angle( $\theta$ ,  $\phi$ ) :  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

### **Definition of viewing angle(CR≥2)**





## 7. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T <sub>OP</sub>	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T <sub>ST</sub>	-30	_	+80	$^{\circ}$
Input Voltage	Vı	V <sub>SS</sub>	_	$V_{DD}$	V
Supply Voltage For Logic	V <sub>DD</sub> -V <sub>SS</sub>	-0.3		7	V
Supply Voltage For LCD	V <sub>DD</sub> -V <sub>o</sub>	-0.3	1	13	V



### **8. Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	3.0	3.3	3.6	٧
		Ta=-20°ℂ	_	_	5.5	V
Supply Voltage For LCD	$V_{DD}$ - $V_0$	Ta=25°ℂ	4.2	4.35	4.5	V
		Ta=70°C	3.5	- ,		V
Input High Volt.	V <sub>IH</sub>	_	0.7 V <sub>DD</sub>	-	$V_{DD}$	V
Input Low Volt.	V <sub>IL</sub>	_	Vss		0.6	V
Output High Volt.	V <sub>OH</sub>	_	0.7 V <sub>DD</sub>		V <sub>DD</sub>	V
Output Low Volt.	V <sub>OL</sub>	-	0	_	0.2 V <sub>DD</sub>	V
Supply Current	I <sub>DD</sub>	V <sub>DD</sub> =3.3V	1.0	1.2	1.5	mA

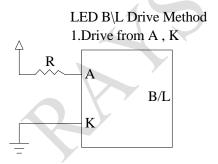


## 9.Backlight Information

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	63	70	84	mA	V=4.2V
Supply Voltage	V	4.0	4.2	4.5	V	- 4
Reverse Voltage	VR	_	_	8	V	-
Luminance (Without LCD)	IV	165	190	_	CD/M <sup>2</sup>	ILED=70mA
Wave Length	λр	568	572	575	nm	ILED=70mA
Life Time	_	_	100000	2	Hr.	ILED≦70mA 25℃,50-60%RH
Color	Yellow Gr	een		) ′		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).





### 10.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

Environmental Test						
Test Item	Content of Test	Test Condition	Note			
High Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	2			
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2			
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1			
High Temperature/ Humidity storage	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2			
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles				
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3			
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time				

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



## 11.Inspection specification

NO	Item	Criterion			AQL	
01	Electrical Testing	defect. 1.2 Missing character, dot 1.3 Display malfunction. 1.4 No function or no display		olay. exceeds product specifications.		0.65
02	Black or white spots on LCD (display only)	2.1 White and black spots three white or black spot		s on display ≤0.25mm, no more than pots present.  nore than two spots or lines within 3mm		2.5
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : $\Phi = (x + y) / 2$ $X \longrightarrow X$ 3.2 Line type : $A$	2 1 7 Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense  2 1 0  Acceptable Q TY Acceptable Q TY Accept no dense  2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		Size Φ $Φ \le 0.20$ $0.20 < Φ \le 0.50$ $0.50 < Φ \le 1.00$ $1.00 < Φ$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion A			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define:			
				thickness	
			Glass thickness a: LCE	) side length	
		L: Electrode pad length	:	_	
				C	
		6.1 General glass chip			
		6.1.1 Chip on panel sui	rface and crack between	panels:	
			N. C.		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing	x≦1/8a	
06	Chipped		area		2.5
	glass	1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more 6.1.2 Corner crack:	e chips, x is total length of	of each chip.	
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≦1/2t	Not over viewing area	x≦1/8a	
		1/2t < z ≦ 2t	Not exceed 1/3k	x≦1/8a	
		⊙ If there are 2 or more	e chips, x is the total leng	gth of each chip.	



NO	Item	Criterion			
		Symbols:			
		x: Chip length y: Chip width z: Chip thickness			
		k: Seal width t: Glass thickness a: LCD side length			
		L: Electrode pad length			
		6.2 Protrusion over terminal :			
		6.2.1 Chip on electrode pad :			
		Z Z	7		
		V X			
		y: Chip width x: Chip length z: Chip thickness			
		$y \le 0.5 \text{mm} \qquad x \le 1/8 \text{a} \qquad 0 < z \le t$			
		6.2.2 Non-conductive portion:			
06	Glass crack	y 12 X X	2.5		
		y: Chip width x: Chip length z: Chip thickness			
		y≤ L			
	/	⊙If the chipped area touches the ITO terminal, over 2/3 of the ITO			
		must remain and be inspected according to electrode terminal specifications.			
		⊙ If the product will be heat sealed by the customer, the alignment			
		mark not be damaged.			
		6.2.3 Substrate protuberance and internal crack.			
		y: width x: length			
		y≤1/3L			
		у			



NO	Item	Criterion	AQL	
07	Cracked glass	The LCD with extensive crack is not acceptable.		
		8.1 Illumination source flickers when lit.	0.65	
08	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5	
00	elements	Using LCD spot, lines and contamination standards.		
		8.3 Backlight doesn't light or color wrong.	0.65	
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5	
09	Bezel	stains or other contamination.		
		9.2 Bezel must comply with job specifications.	0.65	
		10.1 COB seal may not have pinholes larger than 0.2mm or		
		contamination.	2.5	
		10.2 COB seal surface may not have pinholes through to the IC.		
		10.3 The height of the COB should not exceed the height	2.5	
		indicated in the assembly diagram.	0.65	
		10.4 There may not be more than 2mm of sealant outside the		
		seal area on the PCB. And there should be no more than	2.5	
		three places.		
		10.5 No oxidation or contamination PCB terminals.		
10	PCB · COB	10.6 Parts on PCB must be the same as on the production	2.5	
		characteristic chart. There should be no wrong parts, missing parts or excess parts.	0.65	
		10.7 The jumper on the PCB should conform to the product		
		characteristic chart.		
	1	10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	0.65	
		screw hold pad, make sure it is smoothed down.		
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5	
		X	2.5	
		Y X * Y<=2mm2		
		11.1 No un-melted solder paste may be present on the PCB.	2.5	
		11.2 No cold solder joints, missing solder connections, oxidation	2.5	
11	Soldering	or icicle.		
		11.3 No residue or solder balls on PCB.	2.5	
		11.4 No short circuits in components on PCB.	0.65	



NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.  12.2 No cracks on interface pin (OLB) of TCP.	2.5
		12.3 No contamination, solder residue or solder balls on product.	0.65
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to	
12	General	sever.  12.6 The residual rosin or tin oil of soldering (component or chip	2.5
	appearance	component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
	packaging specification	12.10 Product packaging must the same as specified on	
		packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	
		12.12 Visual defect outside of VA is not considered to be rejection.	



#### 12. Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.
- (8) Raystar have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Raystar have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Raystar have the right to modify the version.)



### 13. Material List of Components for RoHs

1. RAYSTAR Display Co., Ltd hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



### 14. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.



Page: 1

		i age. i			
	LCM Sample	Estimate Feedback Sheet			
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating Temperature:	□ Pass	□ NG ,			
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:	1				
2 · Mechanical Specification :					
1. PCB Size:	□ Pass	□ NG ,			
2.Frame Size :	□ Pass	□ NG ,			
3.Materal of Frame:	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to PCB:	□ Pass	□ NG ,			
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :					
1.Pitch of Connector:	□ Pass	□ NG ,			
2.Hole size of Connector:	□ Pass	□ NG ,			
3.Mounting Hole size:	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Referen	ce for LED Ty	pe) :   Pass   NG ,			
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG ,			

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Page: 2

Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage:	□ Pass	□ NG ,			
2.Supply Current:	□ Pass	□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD :	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage Output:	□ Pass	□ NG ,			
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
6 · <u>Summary</u> :					
Sales signature :					
Customer Signature :					